MSKSEMI 美森科













ESD

TSS

MOV

GDT

PLED

S9013-MS

Product specification





TRANSISTOR (NPN)

FEATURES

- High Collector Current.
- Complementary to S9012-MS.
- Excellent hFE Linearity.

Reference News

PACKAGE	MARKING		
1 2 3	1. BASE 2. EMITTER 3.COLLECTOR	J3	
SOT-23			

MAXIMUM RATINGS (Ta=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-Base Voltage	40	V
V _{CEO}	Collector-Emitter Voltage	25	V
V _{EBO}	Emitter-Base Voltage	5	V
lc	Collector Current	500	mA
Pc	Collector Power Dissipation	300	mW
R, JA	Thermal Resistance From Junction To Ambient	416	°C/W
Tj	Junction Temperature	150	℃
T _{stg}	Storage Temperature	<i>-</i> 55∼+150	°C

ELECTRICAL CHARACTERISTICS (Ta=25℃ unless otherwise specified)

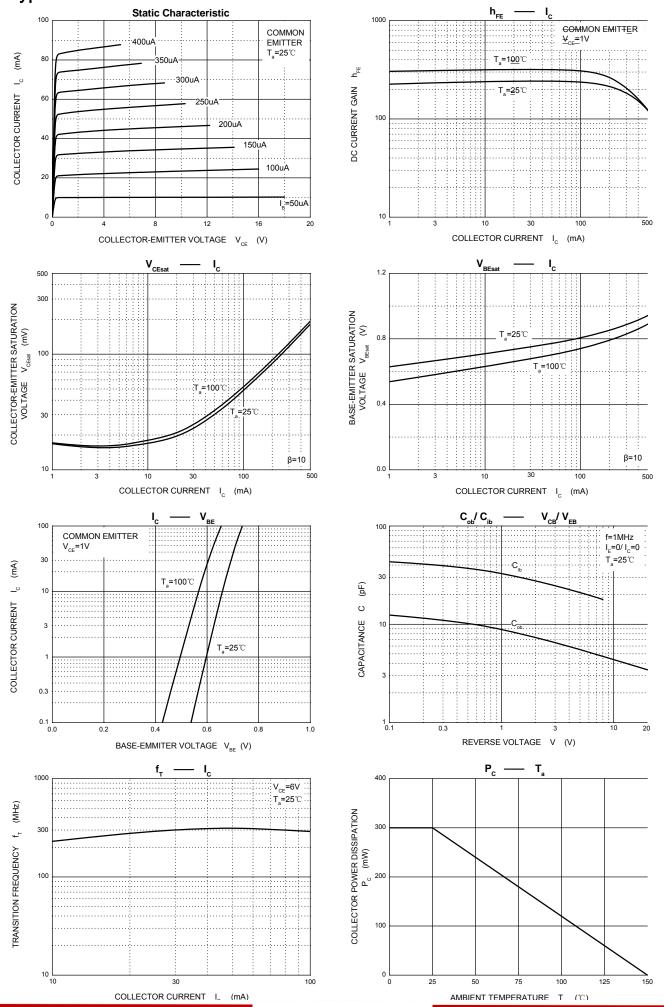
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =0.1mA, I _E =0	40			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	25			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =0.1mA, I _C =0	5			V
Collector cut-off current	Ісво	V _{CB} =40V, I _E =0			0.1	uA
Collector cut-off current	Iceo	V _{CE} =20V, I _B =0			0.1	uA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			0.1	uA
DC surrent sain	h _{FE(1)}	V _{CE} =1V, I _C =50mA	120		400	
DC current gain	h _{FE(2)}	V _{CE} =1V, I _C =500mA	40			
Collector-emitter saturation voltage	V _{CE(sat)}	lc=500mA, I _B =50mA			0.6	V
Base-emitter saturation voltage	V _{BE(sat)}	lc=500mA, l _B =50mA			1.2	V
Base-emitter voltage	V _{BE}	V _{CB} =1V,I _C =10mA,			0.7	V
Transition frequency	f⊤	V _{CE} =6V,I _C =20mA, f=30MHz	150			MHz
Collector output capacitance	C _{ob}	V _{CB} =6V, I _E =0, f=1MHz			8	pF

CLASSIFICATION OF hfE(1)

RANK	L	Н	J
RANGE	120-200	200-350	300-400

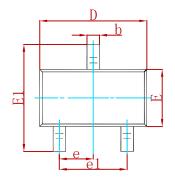


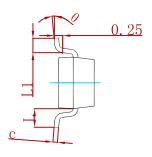
Typical Characterisitics

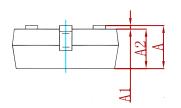




PACKAGE MECHANICAL DATA

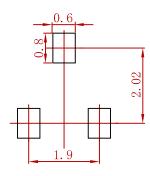






Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.03	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.02	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
S9013-MS	SOT-23	3000









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